

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0	0.41	0.03
	Doped silicon	Silicon (Si)	7440-21-3	0.41	99.59	8.17
Subtotal				0.41	100	8.2
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03	10.0	0.54
	Silver alloy	Silver (Ag)	7440-22-4	0.01	2.0	0.11
	Lead alloy	Lead (Pb)	7439-92-1	0.24	88.0	4.75
Subtotal				0.28	100	5.4
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.41	100.0	8.16
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	66.82	99.91	1338.79
Subtotal				66.88	100	1339.99
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.03	100.0	20.68
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.39	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.1	10.0	62.1
	Filler	Silica fused	60676-86-0	23.25	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.1	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.15	0.5	3.1
Subtotal				30.99	100	621
Total				100	100	2003.43

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